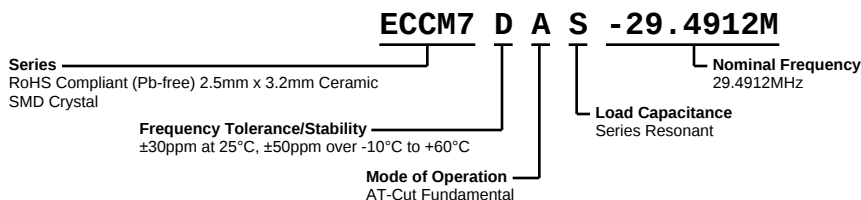


ECCM7DAS-29.4912M



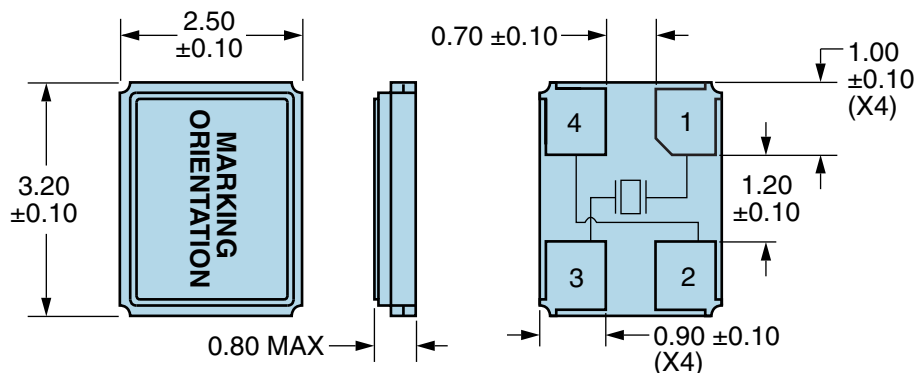
ELECTRICAL SPECIFICATIONS

Nominal Frequency	29.4912MHz
Frequency Tolerance/Stability	$\pm 30\text{ppm}$ at 25°C , $\pm 50\text{ppm}$ over -10°C to $+60^\circ\text{C}$
Aging at 25°C	$\pm 3\text{ppm}/\text{Year}$ Maximum
Load Capacitance	Series Resonant
Shunt Capacitance (C0)	5pF Maximum
Equivalent Series Resistance	80 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	100 μ Watts Maximum
Crystal Cut	AT-Cut
Spurious Response	>3dB (from Fo to Fo +5000ppm)
Storage Temperature Range	-40°C to $+85^\circ\text{C}$
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

MECHANICAL DIMENSIONS (all dimensions in millimeters)



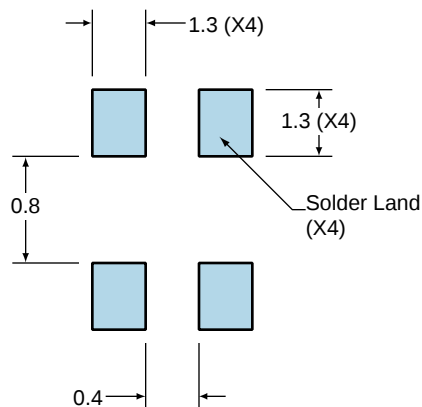
PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	E29.4 E=Ecliptek Designator
2	XXXXX XXXXX=Ecliptek Manufacturing Identifier

ECCM7DAS-29.4912M

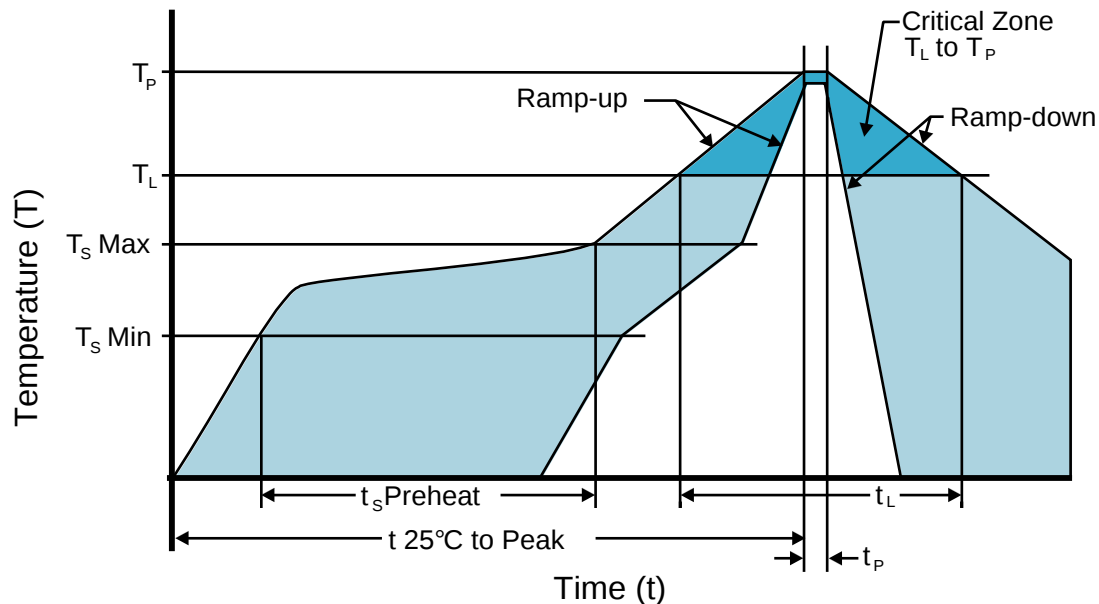
Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ± 0.1

Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T_s MAX to T_L (Ramp-up Rate)	3°C/second Maximum
--	--------------------

Preheat

- Temperature Minimum (T _s MIN)	150°C
- Temperature Typical (T _s TYP)	175°C
- Temperature Maximum (T _s MAX)	200°C
- Time (t _s MIN)	60 - 180 Seconds

Ramp-up Rate (T_L to T_P)	3°C/second Maximum
--	--------------------

Time Maintained Above:

- Temperature (T _L)	217°C
- Time (t _L)	60 - 150 Seconds

Peak Temperature (T_P)	260°C Maximum for 10 Seconds Maximum
---	--------------------------------------

Target Peak Temperature (T_P Target)	250°C +0/-5°C
---	---------------

Time within 5°C of actual peak (t_p)	20 - 40 seconds
---	-----------------

Ramp-down Rate	6°C/second Maximum
-----------------------	--------------------

Time 25°C to Peak Temperature (t)	8 minutes Maximum
--	-------------------

Moisture Sensitivity Level	Level 1
-----------------------------------	---------

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C

T_S MAX to T_L (Ramp-up Rate)	5°C/second Maximum
-----------------------------------	--------------------

Preheat

- Temperature Minimum (T_S MIN)	N/A
- Temperature Typical (T_S TYP)	150°C
- Temperature Maximum (T_S MAX)	N/A
- Time (t_s MIN)	30 - 60 Seconds

Ramp-up Rate (T_L to T_P)	5°C/second Maximum
---------------------------------	--------------------

Time Maintained Above:

- Temperature (T_L)	150°C
- Time (t_L)	200 Seconds Maximum

Peak Temperature (T_P)	245°C Maximum
----------------------------	---------------

Target Peak Temperature (T_P Target)	245°C Maximum 2 Times / 230°C Maximum 1 Time
---	--

Time within 5°C of actual peak (t_p)	10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time
--	--

Ramp-down Rate	5°C/second Maximum
----------------	--------------------

Time 25°C to Peak Temperature (t)	N/A
-----------------------------------	-----

Moisture Sensitivity Level	Level 1
----------------------------	---------

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.